



Session Title:	[WB1] Materials and Innovation
Session Date:	November 22 (Wed.), 2023
Session Time:	08:30-10:20
Session Room:	Room B (Grand Ballroom 1, 2F)
Session Chair:	Prof. Gu-Sung Kim (Kangnam Univ., Korea)

[WB1-1] [Invited] **08:30-09:00**

Advanced Packaging Materials and Evaluation Platform at Resonac

Hidenori Abe, Sadaaki Katoh, Kosuke Murai, and Masashi Minami (Resonac, Japan)

[WB1-2] [Invited] **09:00-09:20**

Low-CTE Epoxy Resin for the Semiconductor Packaging

Sang-yong Tak, Eun-joo Kim, and Dae-bong Yoon (Samhwa Paints Ind Co., Ltd., Korea)

[WB1-3] [Invited] **09:20-09:40**

Fluidic Self-Assembly Packaging: The Future of Microchip Transfer Technologies in MicroLED Display

Daewon Lee (Myongji Univ., Korea)

[WB1-4] **09:40-10:00**

Study on Finite Element Analysis for Interposer Structures

Cheong-Ha Jung and Gu-sung Kim (Kangnam Univ., Korea)

[WB1-5] **10:00-10:20**

Ultra-Thin Heterogeneous Integration via Transfer Printing

Uhyeon Kim and Seok Kim (POSTECH, Korea)